



AAEON Technology INC.
ISO-9001/ISO-14001 Certified
Industrial Automation PCs

PCM-4896L

Thermal Image Analysis Report

Release Date : MAY.30, 2002

Issue Stamp

QA Manager

QE Manager

Test Engineer

Thermal Image Analysis

I . Model Name: PCM-4896L C1.0

II . Description: AIO Compact Board. GX1. LCD/Ethernet/Audio/4COMs, CPU-300.

III . Date: MAY.30, 2002

IV . Measure Site: AAEON QE Dept.

V . Issued by : Linda Sun

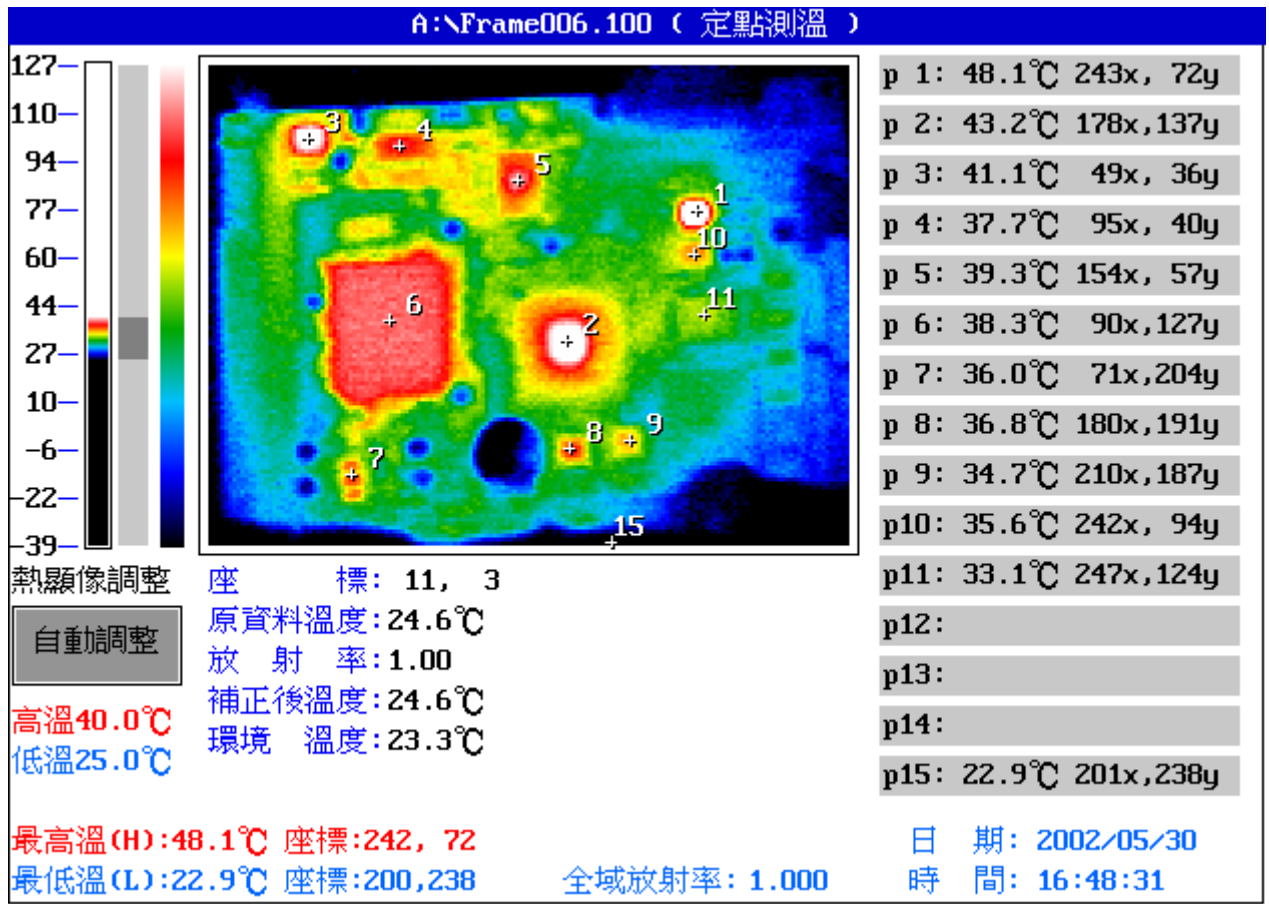
VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.

VII. Simulation Environment:

- **Temperature: 22.9 degrees C**
- **CPU: NS CPU.BGA GX1-300B 2.0V 85C**
- **RAM: NEC D4564841G5-A80-9JF PC100 64 MB**
- **Hardware: Fujitsu MPC3043AP-E 4.3GB**
- **Application Software: BurnIn Test V2.2 Pro**
- **Take Picture Time: Power on 30 minutes after**

Temperature Profile Test:

Component Side:



Point	Position	Describe	Ts	Tm	Note
1	U22	AD1819BJST		48.1°C	
2	U14	N.S.CS5530A		43.2°C	
3	Q1	AMS1083CM		41.1°C	
4	U5	ICS.MK1491-06S		37.7°C	
5	U10	RTL8139C(L)		39.3°C	
6	U7	NS CPU.BGA GX1-300B 2.0V 85C		38.3°C	
7	L1	COIL.C5052-12A08YDP		36.0°C	
8	U13	EPM7032TC44-15		36.8°C	
9	U19	PALCE16V8H-25JC/4		34.7°C	
10	U23	LM4863M		35.6°C	
11	U25	ITE.IT8661F		33.1°C	
12				°C	
13				°C	
14				°C	
15		The Room Temperature		22.9°C	

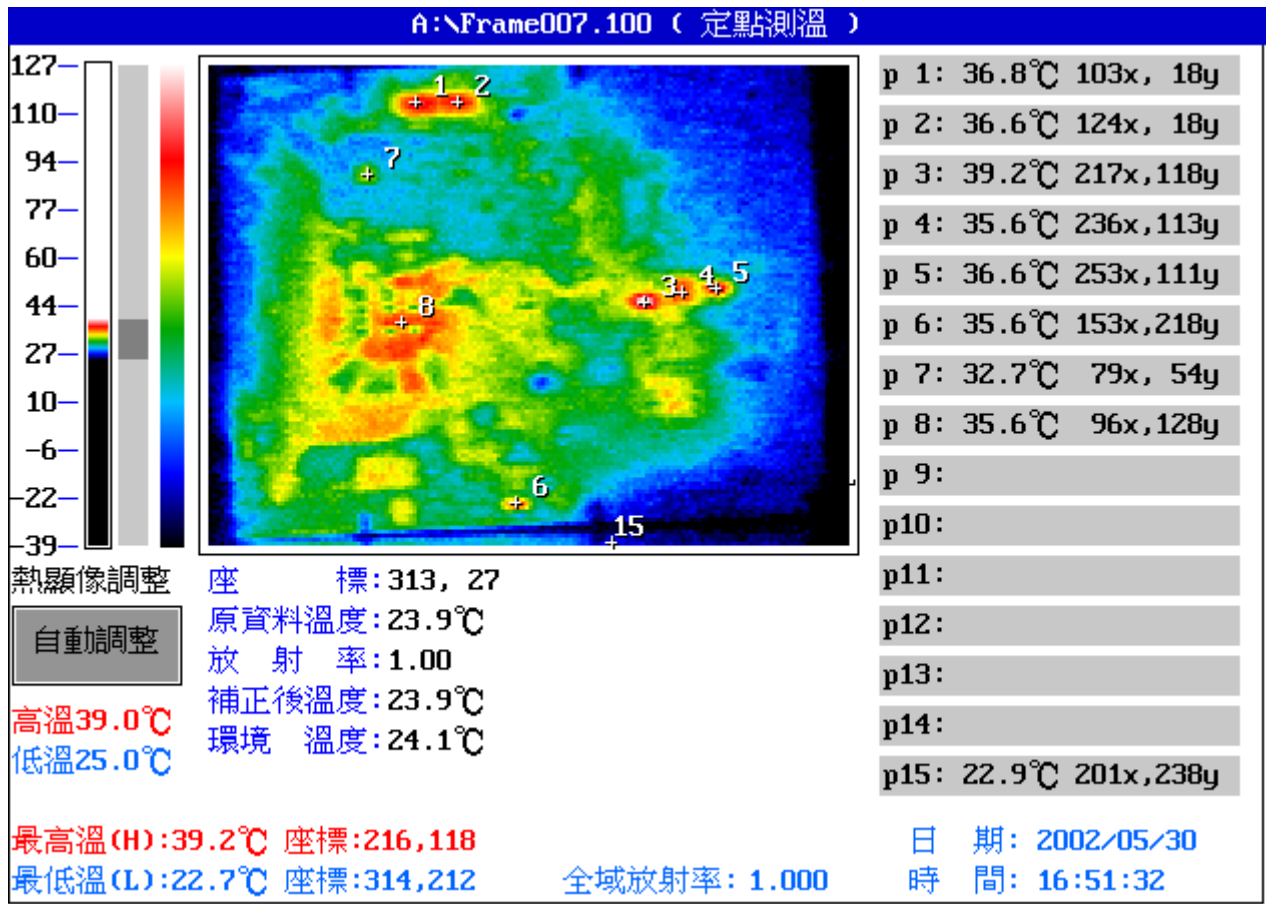
1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)

Temperature Profile Test:

Solder Side:



Point	Position	Describe	Ts	Tm	Note
1	U34	74F373DT		36.8°C	
2	U35	74F373DT		36.6°C	
3	U37	SN74ALS245ADBLE		39.2°C	
4	U36	PALCE16V8H-25JC/4		35.6°C	
5	U38	SN74F174ADR		36.6°C	
6	Q10	UNISEM.US1010CY		35.6°C	
7	ZD1	MBRS340T3		32.7°C	
8		Open space		35.6°C	
9				°C	
10				°C	
11				°C	
12				°C	
13				°C	
14				°C	
15		The Room Temperature		22.9°C	

1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)